

REMARKS

Claims 1-3, 6-16, 18-21 and 32-42 remain pending in the current Application. Claims 1, 3, and 37 have been amended; and claim 4 has been cancelled. Applicants submit that the amendments do not add new matter to the current Application. All the amendments herein have been made in order to clarify the claims and not for prior art reasons. Applicants also submit that (1) no amendment made was related to the statutory requirements of patentability unless expressly stated herein, and (2) no amendment made was for the purpose of narrowing the scope of any claim, unless Applicants have argued herein that such amendment was made to distinguish over a particular reference or combination of references.

The Examiner has indicated that claims 3 and 4 would be allowable if rewritten in independent form. Therefore, in order to further prosecution, Applicants have amended claim 1 to include the elements of claim 4 and have thus cancelled claim 4, and Applicants have rewritten claim 3 into independent form. Therefore, Applicants submit that claims 1 and 3 are allowable. Also, Applicants submit that claims 2, 6-12, and 32 are also allowable since they depend directly or indirectly from allowable claim 1.

Applicants submit that claim 37 is allowable over US 2002/0016013A1 (hereinafter referred to as Iketani) because Iketani does not teach or suggest a partial saw process, as claimed in claim 37. However, Applicants have amended claim 37 in order to further clarify the partial saw process. Claim 37 states that the partial saw process leaves at least a portion of the encapsulation between at least two of the plurality of semiconductor devices. For example, see Fig. 3 of the current Application. Iketani does not teach or suggest this partial saw process. As seen in Figures 7A, 8A, and 10A and as described in paragraph 56 of Iketani, the cutting depth during the dicing process is such that the dicing blade reaches and penetrates the surface of the adhesive sheet 50. Thus, it goes entirely through the encapsulation and is therefore not a partial saw process. Therefore, for at least these reasons, Applicant submit that claim 37 is allowable over Iketani. Claims 38-42 depend directly or indirectly from allowable claim 37 and are therefore also allowable.

Conclusion

Although Applicants may disagree with statements made by the Examiner in reference to the claims and the cited references, Applicants are not discussing all these statements in the current Office Action, yet reserve the right to address them at a later time if necessary.

Applicants respectfully solicit allowance of the pending claims. Contact me if there are any issues regarding this communication or the current Application.

If Applicant has overlooked any additional fees, or if any overpayment has been made, the Commissioner is hereby authorized to credit or debit Deposit Account 503079, Freescale Semiconductor, Inc.

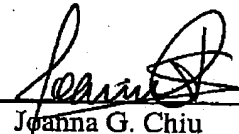
Respectfully submitted,

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